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### **FQP50N06**

#### **60V N-Channel MOSFET**

#### **General Description**

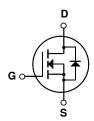
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as automotive, DC/ DC converters, and high efficiency switching for power management in portable and battery operated products.

#### **Features**

- 50A, 60V,  $R_{DS(on)}$  = 0.022 $\Omega$  @ $V_{GS}$  = 10 V • Low gate charge ( typical 31 nC)
- Low Crss (typical 65 pF)
- Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability
- 175°C maximum junction temperature rating





#### **Absolute Maximum Ratings** T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQP50N06	Units
V <sub>DSS</sub>	Drain-Source Voltage		60	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C	C)	50	А
	- Continuous (T <sub>C</sub> = 100	°C)	35.4	А
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	200	А
V <sub>GSS</sub>	Gate-Source Voltage		± 25	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	490	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	50	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	12	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	7.0	V/ns
$P_{D}$	Power Dissipation (T <sub>C</sub> = 25°C)		120	W
	- Derate above 25°C		0.8	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +175	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

#### **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.24	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°	C	0.06		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V			1	μА
		V <sub>DS</sub> = 48 V, T <sub>C</sub> = 150°C			10	μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 25 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -25 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 25 \text{ A}$		0.018	0.022	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 25 V, I <sub>D</sub> = 25 A (Note 4	)	22		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		1180 440 65	1540 580 90	pF pF
Switchi	ing Characteristics		<u> </u>	l	<u>I</u>	
t <sub>d(on)</sub>	Turn-On Delay Time	V 00 V I 05 A		15	40	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 30 \text{ V}, I_{D} = 25 \text{ A},$		105	220	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$R_G = 25 \Omega$		60	130	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4, 5	)	65	140	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 48 V, I <sub>D</sub> = 50 A,		31	41	nC
Q <sub>gs</sub>	Gate-Source Charge	$V_{GS} = 10 \text{ V}$		8		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4, 5	)	13		nC
	Saura Diada Obara Mariatian a	ad Massimosoma Datinana	<b>"</b>		1	
I <sub>S</sub>	Source Diode Characteristics and Maximum Ratings  Maximum Continuous Drain-Source Diode Forward Current				50	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				200	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 50 A			1.5	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_S = 50 \text{ A},$		52		ns
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**Notes:**1. Repetitive Rating: Pulse width limited by maximum junction temperature 2. L = 230μH, I<sub>AS</sub> = 50A, V<sub>DD</sub> = 25V, R<sub>G</sub> = 25 Ω, Starting T<sub>J</sub> = 25°C 3. I<sub>SD</sub> = 50A, di/dt  $\leq$  300A/μs, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 4. Pulse Test: Pulse width  $\leq$  300μs, Duty cycle  $\leq$  2% 5. Essentially independent of operating temperature

### **Typical Characteristics**

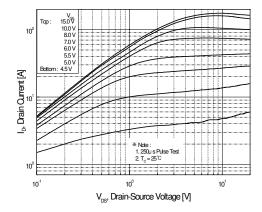


Figure 1. On-Region Characteristics

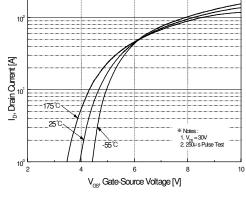


Figure 2. Transfer Characteristics

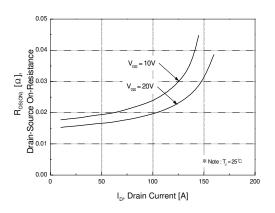


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

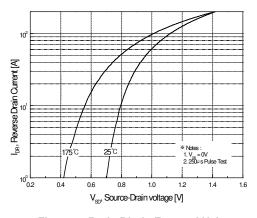


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

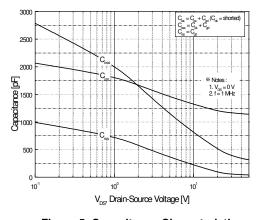


Figure 5. Capacitance Characteristics

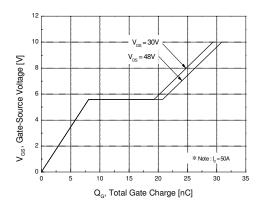


Figure 6. Gate Charge Characteristics

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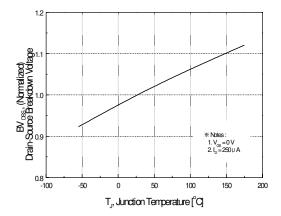


Figure 7. Breakdown Voltage Variation vs. Temperature

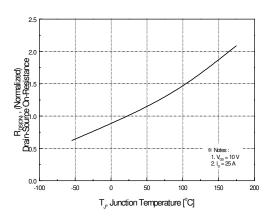


Figure 8. On-Resistance Variation vs. Temperature

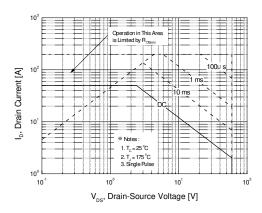


Figure 9. Maximum Safe Operating Area

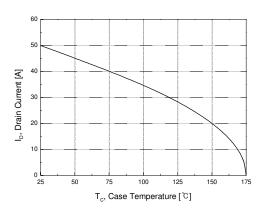


Figure 10. Maximum Drain Current vs. Case Temperature

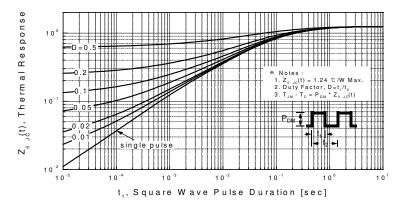
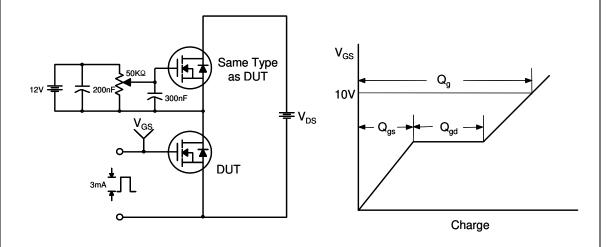


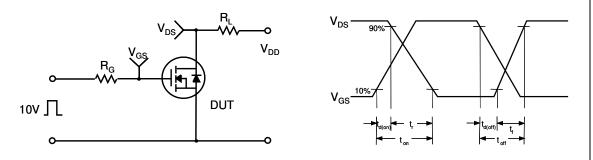
Figure 11. Transient Thermal Response Curve

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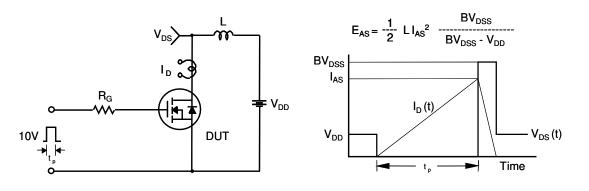
#### **Gate Charge Test Circuit & Waveform**



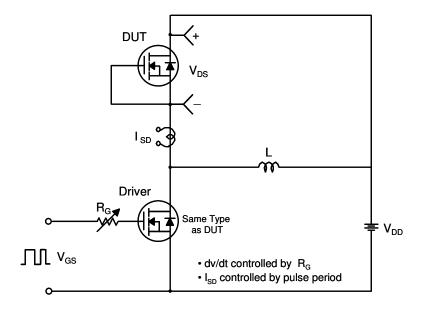
#### **Resistive Switching Test Circuit & Waveforms**

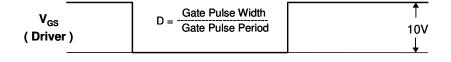


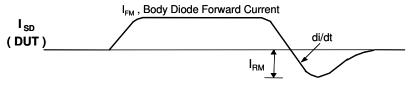
#### **Unclamped Inductive Switching Test Circuit & Waveforms**



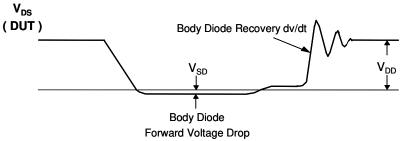
#### Peak Diode Recovery dv/dt Test Circuit & Waveforms

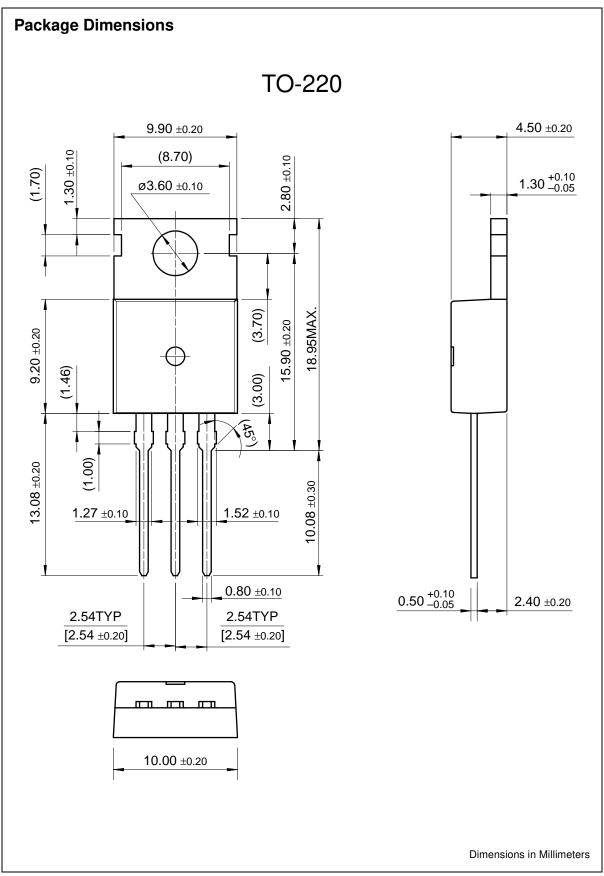






Body Diode Reverse Current





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